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New Joint Technology and Circuits Sessions Planned For 2012

2012 Symposia on VLSI Technology and Circuits Announce Calls for Papers

HONOLULU, HAWAII – October 24, 2011 -- The 2012 Symposia on VLSI Technology & Circuits, to be held at the Hilton Hawaiian Village here June 12-14, 2012 (Technology) and June 13-15, 2012 (Circuits), announce their respective Calls for Papers, seeking innovative, original work in the areas described below. The Calls for Papers can be found at www.vlsisymposium.org. The deadline for paper submissions to both conferences is January 23, 2012. The late-news deadline for the VLSI Technology Conference is March 22, 2012; there is no late-news submission available for the Circuits Conference.

These annual joint symposia are the premier mid-year gatherings for the advancement of microelectronics technology and circuits, and a single registration fee covers both events. They overlap specifically to provide the opportunity for technologists and circuit/system designers to interact and attend presentations by each other in an open forum, offering unique opportunities that other leading conferences in each area can't replicate. In addition -- for the first time -- joint technology and circuit focus sessions will be held in 2012.

These interactions are augmented with short courses, invited speakers and evening rump sessions. The VLSI Technology Symposium began in 1981, while the VLSI Circuits Symposium was added in 1987. The two meetings have been held together ever since, rotating annually between Japan and Hawaii.

The VLSI Technology Symposium seeks papers in the following areas:

- New concepts and breakthroughs in VLSI processes and devices for memory, logic, I/O, and I/F
- Advanced gate stacks and interconnects
- Advanced lithography and fine-patterning technologies
- New functional devices beyond CMOS with a path for VLSI implementation
- Packaging of VLSI devices including 3D-system integration
- Advanced device analysis, materials and modeling
- Reliability related to the above devices
- Theory and fundamentals related to the above devices

- New concepts and technologies for VLSI manufacturing
- Heterogeneous integration of non-Si materials/devices on large Si substrates

The VLSI Circuits Symposium seeks papers in the following areas:

- RF and wireless communications circuits and architecture
- Wireline transceiver and I/O design
- Digital circuit techniques
- Clock generation and distribution
- Analog and mixed signal
- Digitally assisted analog and analog-assisted digital circuits
- Memory circuits and architectures
- Power minimization techniques and circuits
- Power management circuits
- Sensor and display circuits

New Joint Circuits & Technology Focus Sessions

In 2012, for the first time, joint circuit and technology focus sessions will be offered in the following special topics of joint interest:

- Design in scaled technologies
- Design enablement
- Memory technology and design
- 3D (TSV) and heterogeneous integration

Paper submissions highlighting major innovations and advances in circuits, designs, tools and methodologies are strongly encouraged. More details are available in the Calls for Papers.

Sponsoring Organizations

The VLSI Technology Symposium is sponsored by the IEEE Electron Devices Society and the Japan Society of Applied Physics, in cooperation with the IEEE Solid State Circuits Society. A limited number of late-news papers highlighting recent and impactful results will be considered. The deadline for late-news papers is March 22, 2012.

The VLSI Circuits Symposium is sponsored by the IEEE Solid-State Circuits Society and the Japan Society of Applied Physics, in cooperation with the Institute of Electronics, Information and Communication Engineers and the IEEE Electron Devices Society.

Further Information and Registration

Visit www.vlsisymposium.org

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